

# DECLARATION FOR PATENT APPLICATION

Docket No. 7777

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled **SEMI-SOLID MOLDING METHOD**, the specification of which (check one)

☒ is attached hereto.  
☐ was filed on \_\_\_\_\_ as Application Serial No. \_\_\_\_\_  
and was amended on \_\_\_\_\_  
(if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a). I hereby claim foreign priority benefits under Title 35, United States Code, Section 119 of the foreign application for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Priority Claimed  
( ) Yes ( ) No

(Number) (Country) (Day/Month/Year Filed)

I hereby claim the benefit under Title 35, United States Code, Section 120 of the United States application below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Registrations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Ser.No.) (Filing Date) (Status-Patented, Pending, Abandoned)

I hereby appoint the following attorneys with full power of appointment, substitution, association and revocation, to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Alan F. Meckstroth Reg. No. 22,607, and  
Matthew R. Jenkins Reg. No. 34,844

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Address all correspondence to: JACOX, MECKSTROTH & JENKINS, 2310 Far Hills Building, Dayton, Ohio 45419-1575

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Richard J. KammInventor's signature  Citizenship USAResidence 879 Bolton Abbey Lane, Vandalia, Ohio 45377 Date January 31, 2002Post Office Address 7475 Webster St., Dayton, Ohio 45414Full name of second joint inventor, if any John L. JorstadInventor's signature  Citizenship USAResidence 9112 Donora Dr., Richmond, Virginia 23229 Date January 24, 2002Post Office Address 7475 Webster St., Dayton, Ohio 45414